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PNP MEDIUM POWER TRANSISTOR

Features

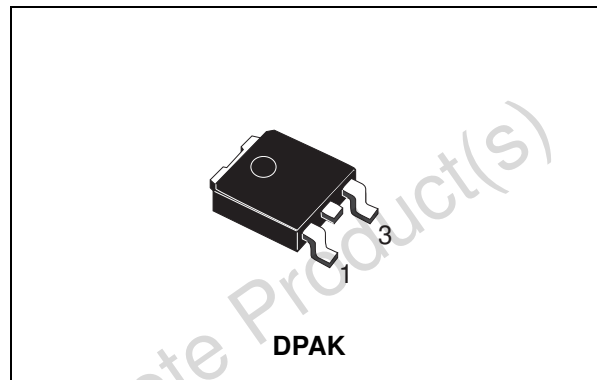
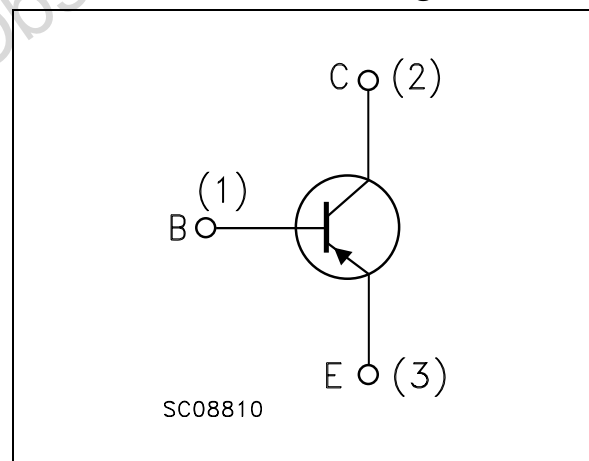
- SURFACE MOUNTING DEVICE IN MEDIUM POWER DPAK PACKAGE
- AVAILABLE IN TAPE & REEL PACKING
- IN COMPLIANCE WITH THE 2002/93/EC EUROPEAN DIRECTIVE

Applications

- VOLTAGE REGULATION
- RELAY DRIVER
- GENERIC SWITCH

Description

The STD826 is PNP transistor manufactured using planar Technology resulting in rugged high performance devices.


Internal Schematic Diagram

Order codes

Part Number	Marking	Package	Packing
STD826T4	D826	DPAK	Tape & reel

1 Absolute Maximum Ratings

Table 1. Absolute Maximum Rating

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-Base Voltage ($I_E = 0$)	-60	V
V_{CEO}	Collector-Emitter Voltage ($I_B = 0$)	-30	V
V_{EBO}	Collector-Base Voltage ($I_C = 0$)	-5	V
I_C	Collector Current	-3	A
I_{CM}	Collector Peak Current ($t_P < 5\text{ms}$)	-6	A
I_B	Base Current	-1	A
I_{BM}	Base Peak Current ($t_P < 5\text{ms}$)	-2	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	15	W
T_{STG}	Storage Temperature	-65 to 150	$^\circ\text{C}$
T_J	Max. Operating Junction Temperature	150	$^\circ\text{C}$

Table 2. Thermal Data

Symbol	Parameter	Value	Unit
$R_{thJ-case}$	Thermal Resistance Junction-Case Max	8.33	$^\circ\text{C/W}$

2 Electrical Characteristics

Table 3. Electrical Characteristics ($T_{CASE} = 25^{\circ}C$; unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{CES}	Collector Cut-off Current ($V_{BE} = 0$)	$V_{CE} = -60V$			-10	μA
I_{CEO}	Collector Cut-off Current ($I_B = 0$)	$V_{CE} = -30V$			-100	μA
I_{EBO}	Emitter Cut-off Current ($I_C = 0$)	$V_{EB} = -5V$			-10	μA
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage ($I_E = 0$)	$I_C = -100\mu A$	-60			V
$V_{(BR)CEO}$ <i>Note: 1</i>	Collector-Emitter Breakdown Voltage ($I_B = 0$)	$I_C = -10\text{ mA}$	-30			V
$V_{(BR)EBO}$	Collector-Emitter Breakdown Voltage ($I_C = 0$)	$I_E = -100\ \mu A$	-5			V
$V_{CE(sat)}$ <i>Note: 1</i>	Collector-Emitter Saturation Voltage	$I_C = -1\text{ A}$ $I_C = -2\text{ A}$ $I_C = -3\text{ A}$	$I_B = -50\text{ mA}$ $I_B = -100\text{ mA}$ $I_B = -150\text{ mA}$		-0.4 -0.7 -1.1	V V V
$V_{BE(sat)}$ <i>Note: 1</i>	Base-Emitter Saturation Voltage	$I_C = -2\text{ A}$	$I_B = -100\text{ mA}$		-1.2	V
h_{FE}	DC Current Gain	$I_C = -100\text{ mA}$ $I_C = -1\text{ A}$ $I_C = -3\text{ A}$	$V_{CE} = -2\text{ V}$ $V_{CE} = -2\text{ V}$ $V_{CE} = -2\text{ V}$	100 80 30	300	
f_T	Transistor Frequency	$V_{CE} = -10\text{ V}$	$I_C = -0.1\text{ A}$		100	MHz

Note: 1 Pulsed duration = 300 μs , duty cycle $\leq 1.5\%$.

2.1 Electrical characteristics (curve)

Figure 1. DC Current Gain

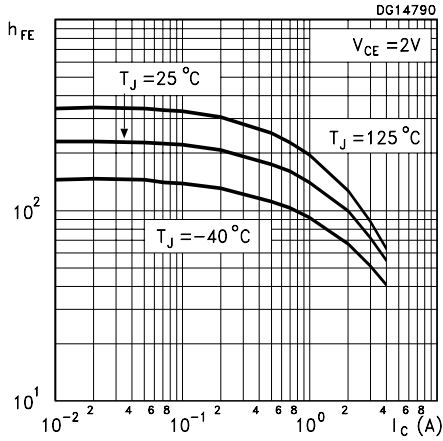


Figure 2. DC Current Gain

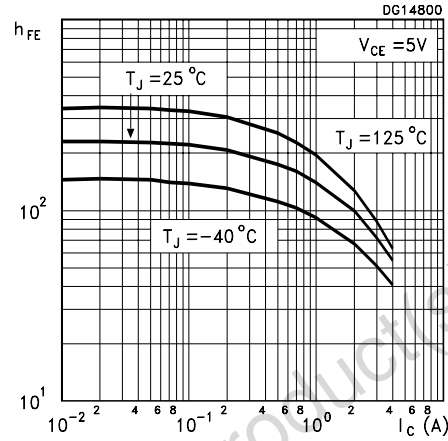


Figure 3. Collector-emitter saturation voltage Figure 4. Base-emitter saturation voltage

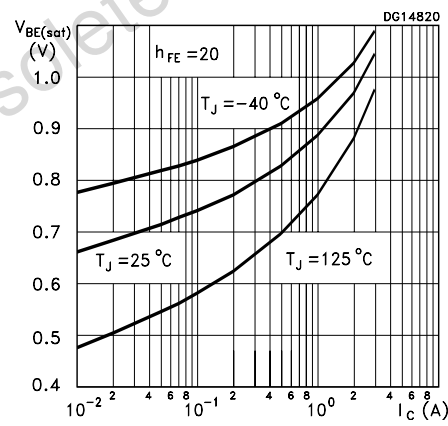
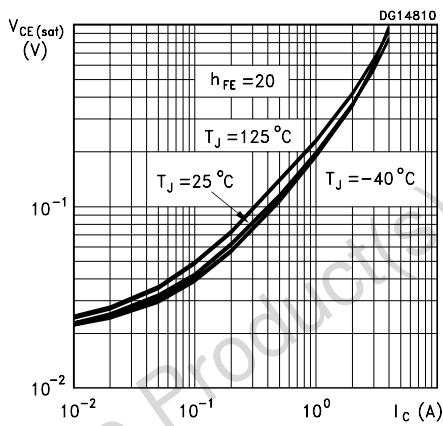


Figure 5. Switching times on resistive load

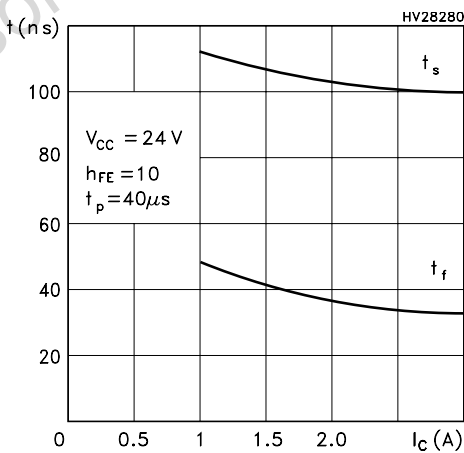


Figure 6. Switching times resistive on load

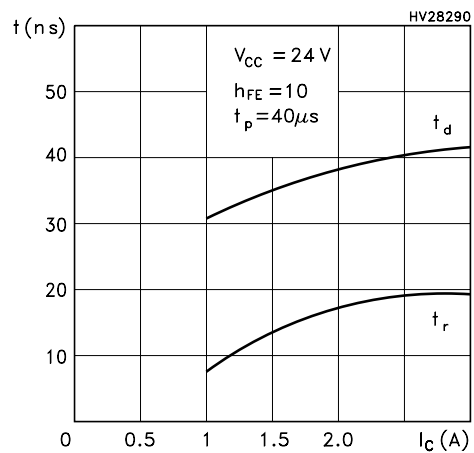
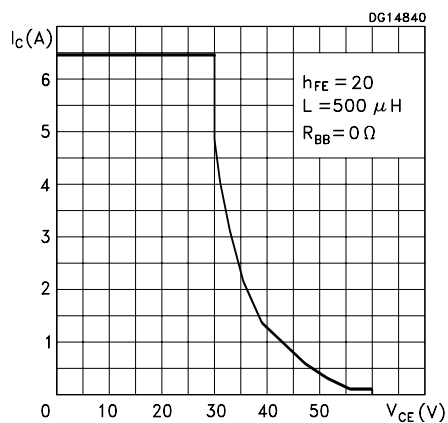


Figure 7. Reverse biased area



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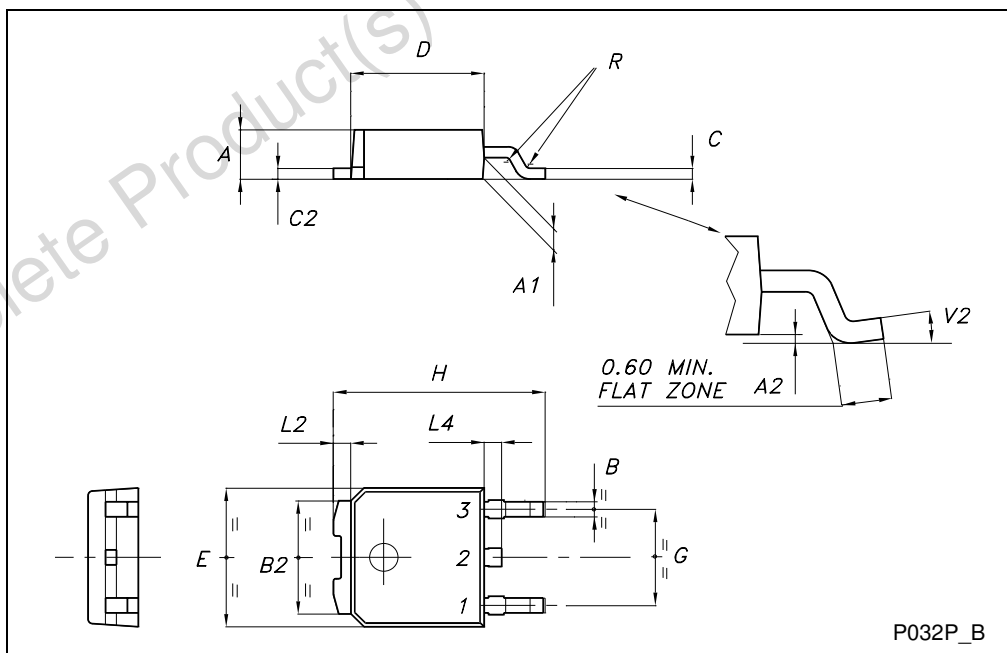
3 Package Mechanical Data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

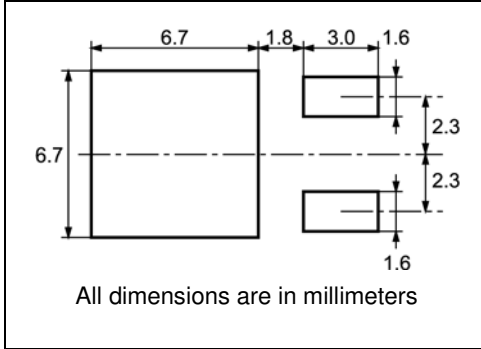
Obsolete Product(s) - Obsolete Product(s)

TO-252 (DPAK) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.213
C	0.45		0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
G	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.398
L2		0.8		0.031		
L4	0.60		1.00	0.024		0.039
V2	0°		8°	0°		0°



DPAK FOOTPRINT



TAPE AND REEL SHIPMENT

REEL MECHANICAL DATA

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A		330		12.992
B	1.5		0.059	
C	12.8	13.2	0.504	0.520
D	20.2		0.795	
G	16.4	18.4	0.645	0.724
N	50		1.968	
T		22.4		0.881

TAPE MECHANICAL DATA

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A0	6.8	7	0.267	0.275
B0	10.4	10.6	0.409	0.417
B1		12.1		0.476
D	1.5	1.6	0.059	0.063
D1	1.5		0.059	
E	1.65	1.85	0.065	0.073
F	7.4	7.6	0.291	0.299
K0	2.55	2.75	0.100	0.108
P0	3.9	4.1	0.153	0.161
P1	7.9	8.1	0.311	0.319
P2	1.9	2.1	0.075	0.082
R	40		1.574	
W	15.7	16.3	0.618	0.641

4 Revision History

Date	Revision	Changes
03-Aug-2005	1	Initial release.

Obsolete Product(s) - Obsolete Product(s)

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